



I3GT022N10

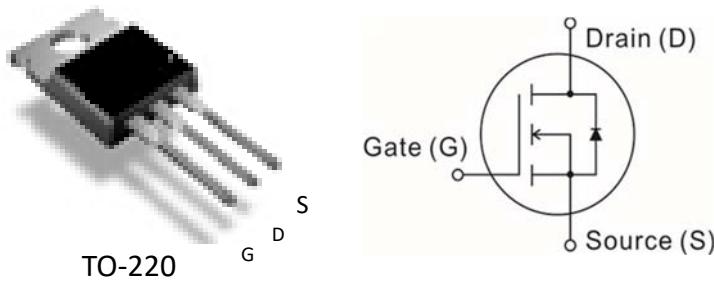
100V N-Channel Power MOSFET

Product Summary

Parameter	Value	Unit
V _{DS} @ T _{jmax}	100	V
R _{DS(on),max} @ V _{GS} = 10 V	2.2	mΩ
I _D @ V _{GS} = 10 V	260	A
P _{tot}	375	W

Features

- * Low on-resistance
- * Low gate threshold voltage
- * Excellent FOM

**Application**

- * Synchronous rectification
- * BMS battery protection
- * DC/AC inverter
- * DC/DC converter

Maximum ratings T_A = 25°C unless otherwise noted

Parameter	Symbol	Limit	Unit
Drain - source voltage	V _{DS}	100	V
Continuous drain current	I _D	260	A
T _c @ 25°C		260	
T _c @ 100°C		180	
Pulsed drain current tp limited by T _j max (Note 1)	I _D pulsed	480	A
Single pulse avalanche energy (Note 2)	E _{AS}	1080	mJ
Gate-source voltage	V _{GS}	± 20	V
Power dissipation	P _{tot}	375	W
Storage temperature range	T _{STG}	- 55 to +175	°C
Operating junction temperature range	T _J	- 55 to +175	°C



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Electrical characteristics $T_A = 25^\circ\text{C}$ unless otherwise specified						
Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
Off characteristics						
Drain-source breakdown voltage	$V_{GS} = 0\text{V}$, $I_D = 1\text{mA}$	BV_{DSS}	100	---	---	V
Gate-source leakage	$V_{GS} = \pm 20\text{V}$, $V_{DS}=0\text{V}$	I_{GSS}	---	---	± 100	nA
Zero gate voltage drain current	$V_{DS}= 100\text{V}$, $V_{GS}= 0\text{V}$, $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$	I_{DSS}	---	0.1	1	uA
---			---	---	100	
On characteristics						
Drain-source on-state resistance	$V_{GS} = 10\text{V}$, $I_D = 100\text{A}$, $T_j=25^\circ\text{C}$	$R_{DS(on)}$	---	1.8	2.2	mΩ
Gate-source threshold voltage	$V_{DS} = V_{GS}$, $I_D = 250\text{uA}$	$V_{GS(th)}$	2.0	3.0	4.0	V
Gate resistance	$F = 1\text{MHz}$, open drain	R_G	---	1.2	---	Ω
Dynamic and switching characteristics-						
Gate-source charge	$V_{DD} = 50\text{V}$, $I_D = 100\text{A}$ $V_{GS} = 0$ to 10V	Q_{gs}	---	53	---	nC
Gate-drain charge		Q_{gd}	---	31	---	
Gate charge total		Q_g	---	155	---	
Turn-on delay time	$V_{DD} = 50\text{V}$, $I_D = 100\text{A}$ $V_{GS} = 10\text{V}$, $R_{G,ext} = 1.6\Omega$	$T_d(\text{on})$	---	44	---	ns
Rise time		T_r	---	36	---	
Turn-off delay time		$T_d(\text{off})$	---	81	---	
Fall time		T_f	---	22	---	
Input capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = 50\text{V}$, $F = 1\text{MHz}$	C_{iss}	---	11100	---	pF
Output capacitance		C_{oss}	---	1730	---	
Reverse transfer capacitance		C_{rss}	---	45	---	

Parameter	Test Conditions	Symbol	Min.	Typ.	Max.	Units
Drain-source diode characteristics and maximum ratings						
Inverse diode forward voltage	$I_S = 100\text{A}$, $V_{GS} = 0\text{V}$	V_{SD}	---	0.9	1.2	V
Reverse recovery time	$V_R = 50\text{V}$, $I_F = 100\text{A}$, $dI_F / dt = 100\text{A} / \mu\text{s}$	t_{rr}	---	95	---	ns
Reverse recovery charge		Q_{rr}	---	295	---	nC

Notes:

1. Repetitive rating : pulsed width limited by maximum junction temperature.
2. $V_{DD}=50\text{V}$, starting $T_j=25^\circ\text{C}$.



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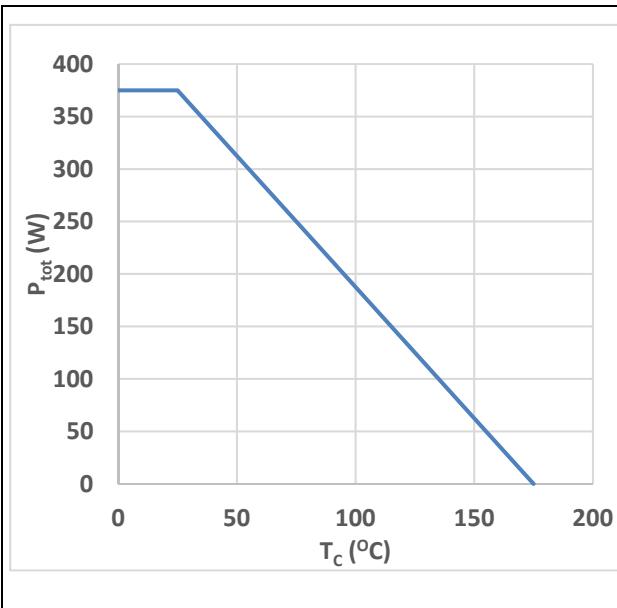
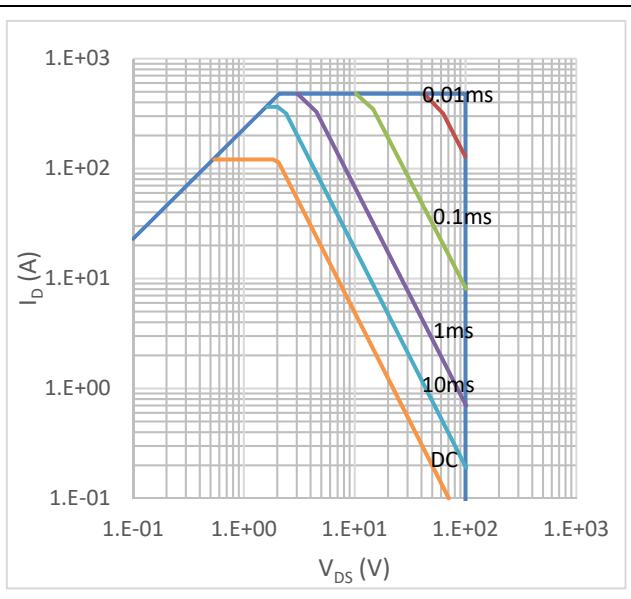
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Thermal characteristics

Thermal resistance junction-to-case	R _{thJC}	0.4	°C / W
Thermal resistance junction-to-ambient	R _{thJA}	62	

Package Marking and Ordering Information

Type / Ordering Code	Package	Packaging	Related Links
I3GT022N10	TO-220	Tube	see Package outline

Electrical characteristics diagrams**Fig 1: Power dissipation** $P_{tot} = f(T_c)$ **Fig 2: Safe operating area** $I_D = f(V_{DS})$; parameter : D = 0, $T_c = 25^\circ C$ 



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Fig 3: Transient thermal impedance

$Z_{thJC} = f(t_p)$; parameter : $D = t_p / T$

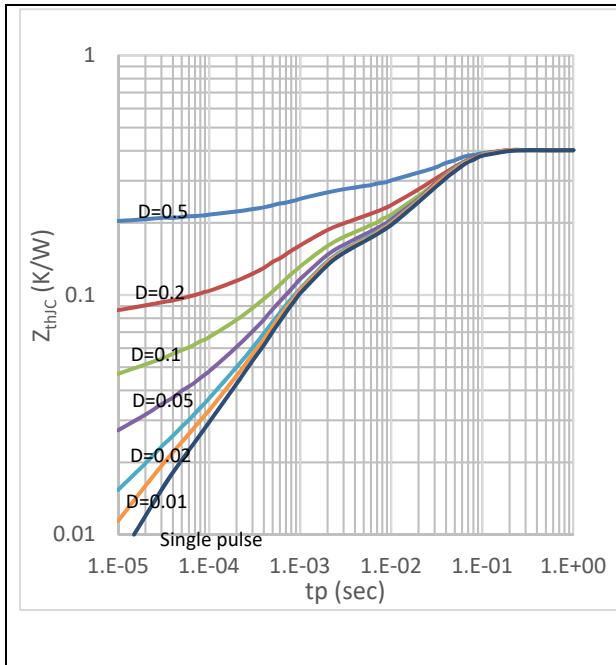


Fig 4: Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25^\circ C$; parameter: V_{GS}

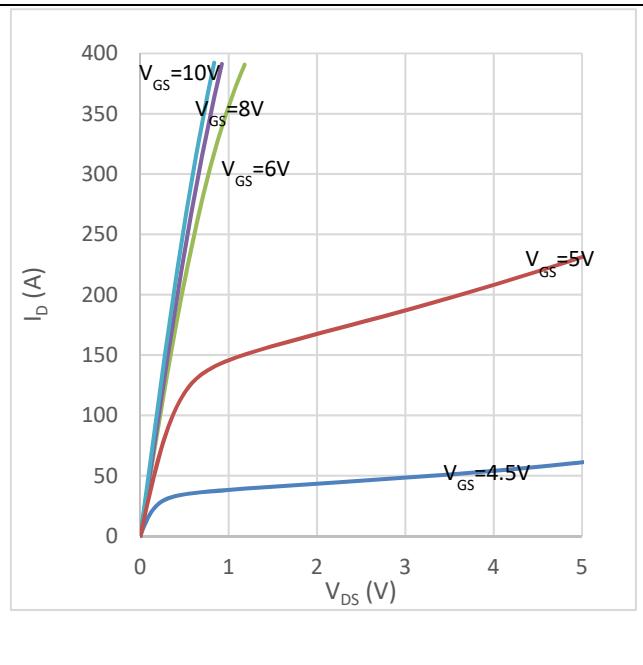


Fig 5: Drain current

$I_D = f(T_c)$; $V_{GS} \geq 10V$

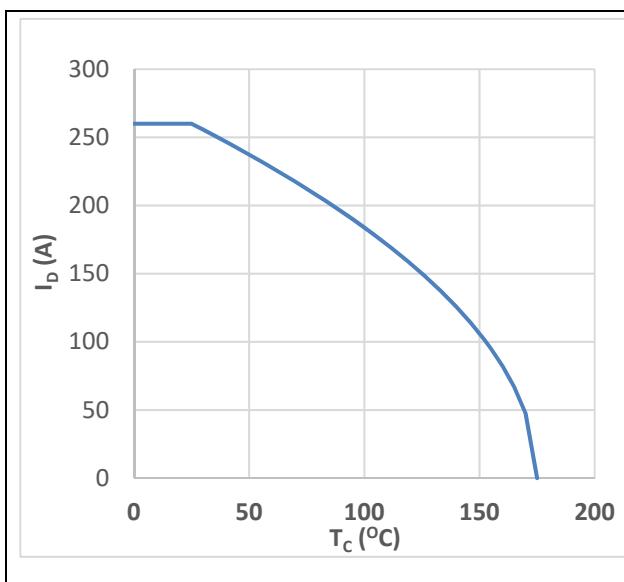
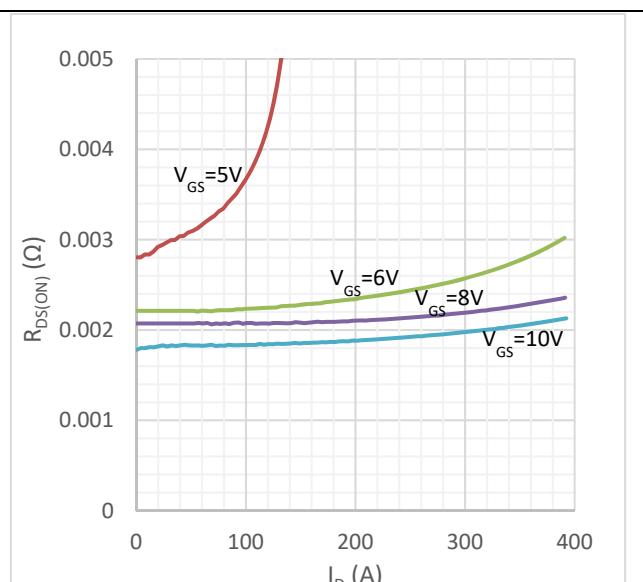


Fig 6: Typ. Drain source on-resistance

$R_{DS(on)} = f(I_D)$; parameter : $t_p = 50\mu S$, $T_j = 25^\circ C$, V_{GS}





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Fig 7: Drain-source on-state resistance

$R_{DS(on)} = f(T_j)$; parameter : $I_D = 100A$, $V_{GS} = 10V$

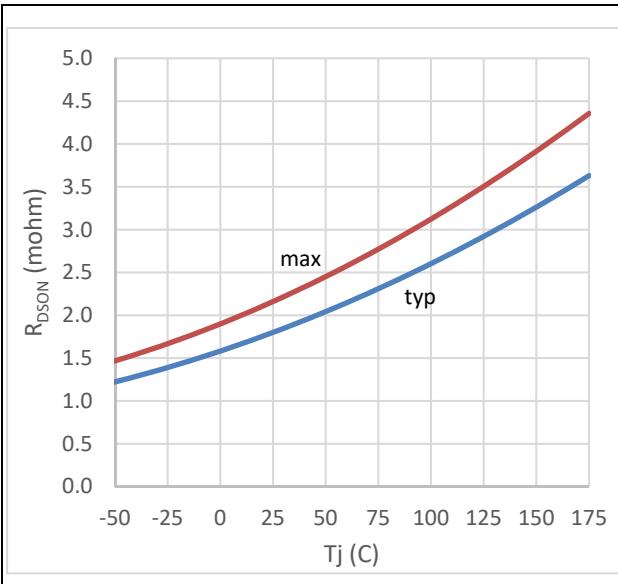


Fig 8: Typ. transfer characteristics

$I_D = f(V_{GS})$; $V_{DS} \geq 2 \times I_D \times R_{DS(on) \text{ max}}$; $T_j = 25^\circ C$; parameter : $t_p = 50 \mu s$

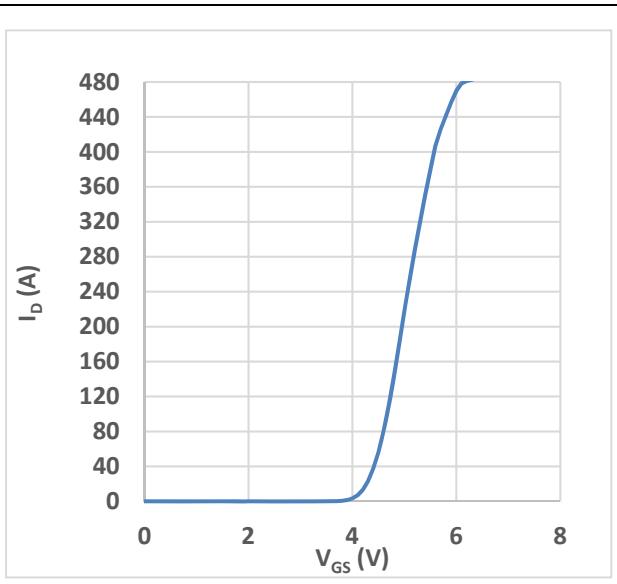


Fig 9: Typ. gate charge

$V_{GS} = f(Q_{GATE})$; $I_D = 100A$ pulsed

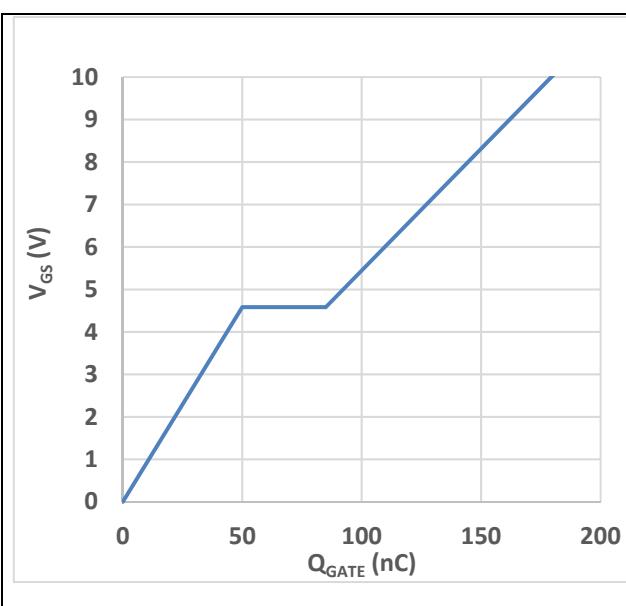
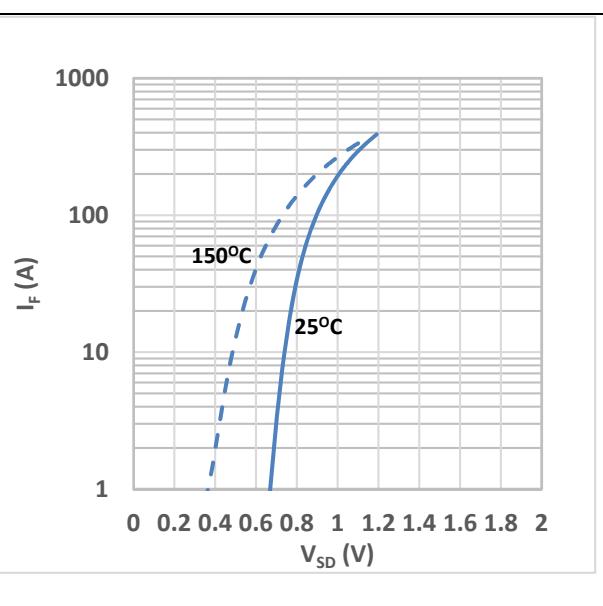


Fig 10: Forward characteristics of body diode

$I_F = f(V_{SD})$; parameter : T_j , $t_p = 20\mu s$





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Fig 11: Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$

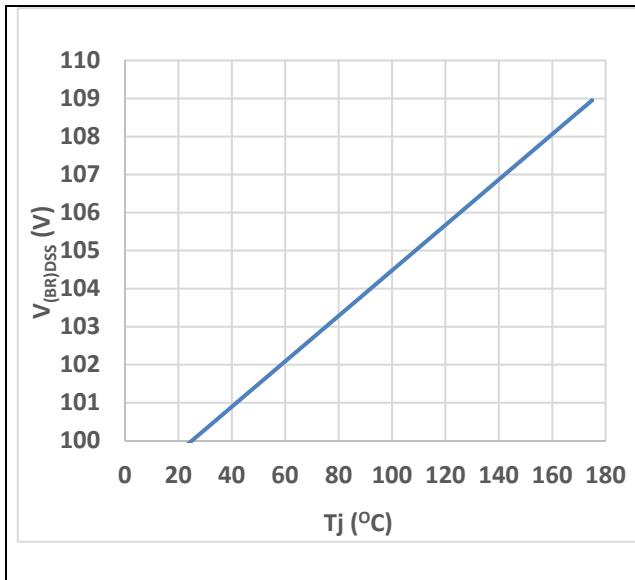


Fig 12: Typ. capacitances

$$C = f(V_{DS}); \text{ parameter : } V_{GS} = 0V, f = 1\text{MHz}$$

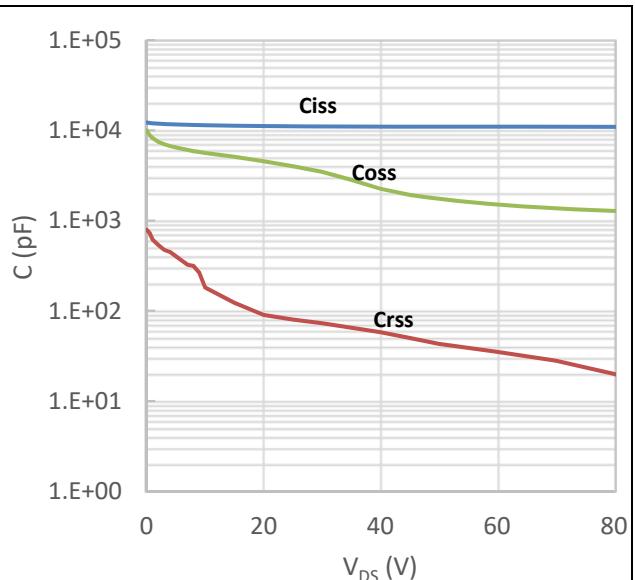
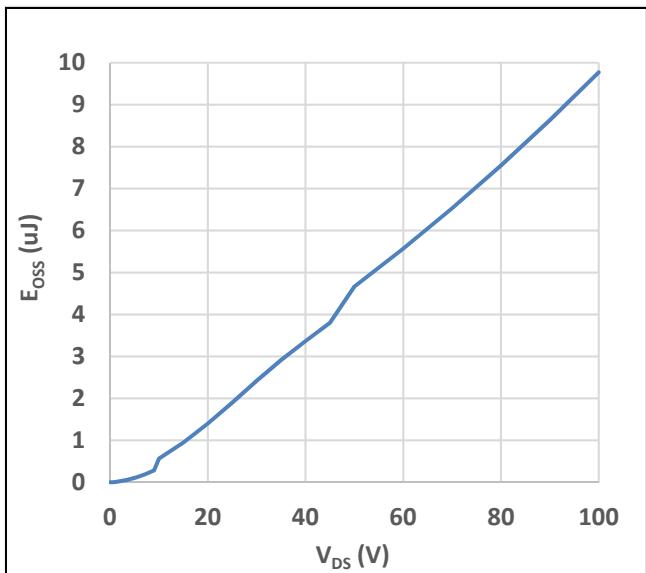
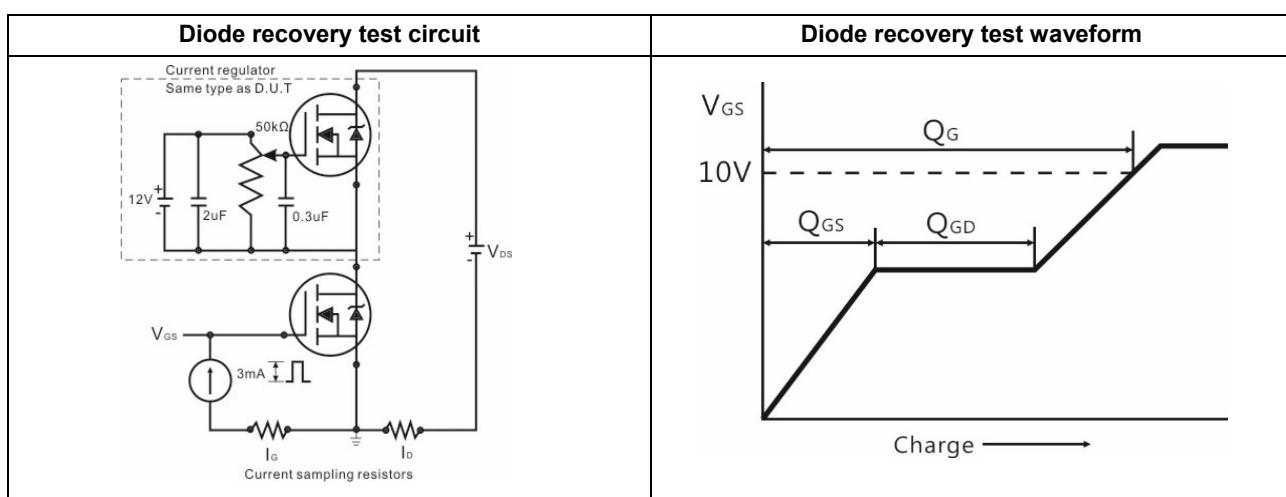
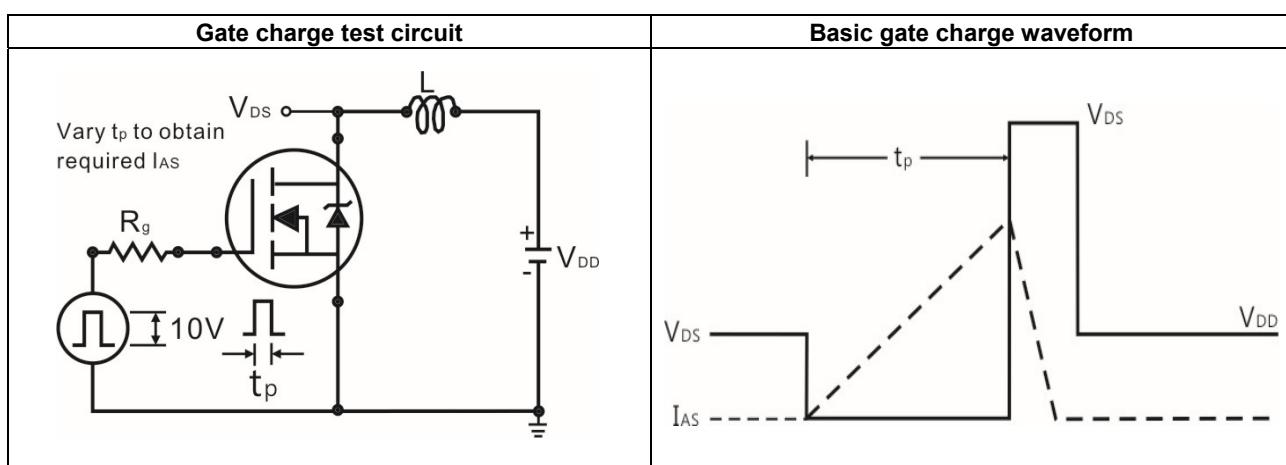
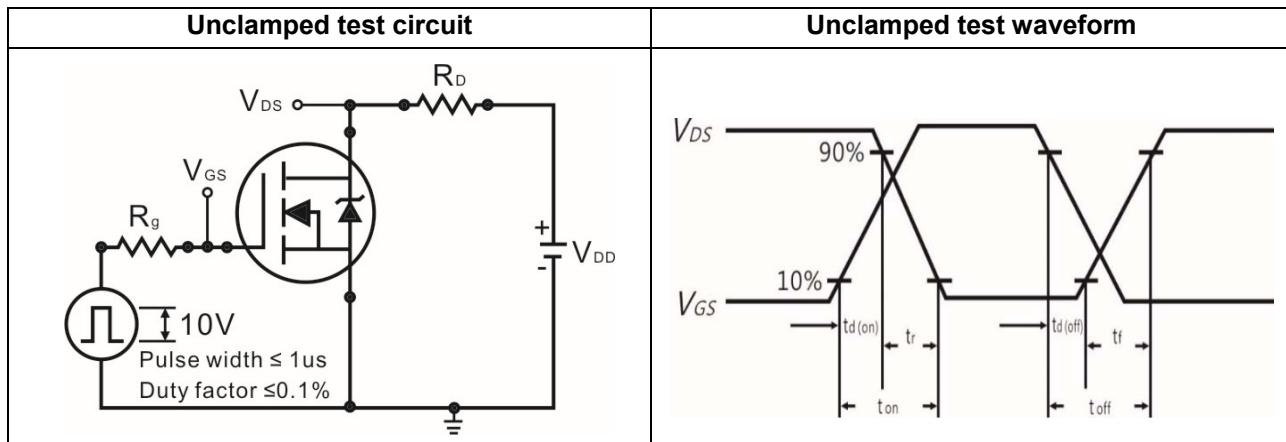


Fig 13: Typ. C_{oss} stored energy

$$E_{oss} = f(V_{DS})$$

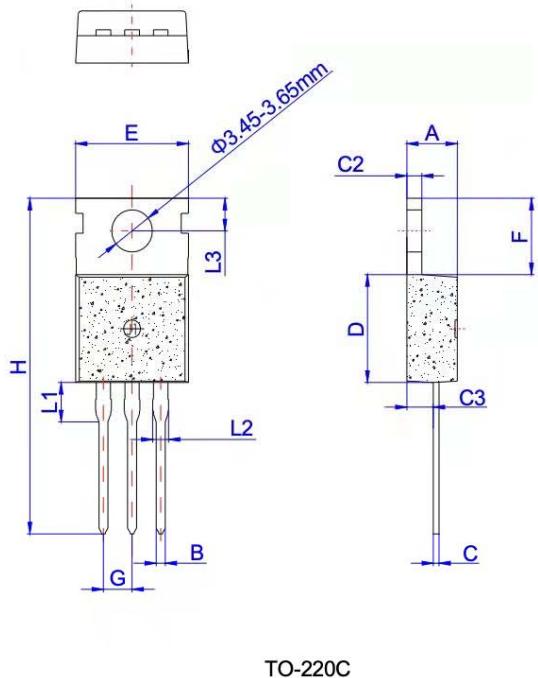


**Test Circuit**



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Package outline**PACKAGE MECHANICAL DATA**

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	0.70		0.90	0.028		0.035
C	0.45		0.60	0.018		0.024
C2	1.23		1.32	0.048		0.052
C3	2.20		2.60	0.087		0.102
D	8.90		9.90	0.350		0.390
E	9.90		10.3	0.390		0.406
F	6.30		6.90	0.248		0.272
G		2.54			0.1	
H	28.0		29.8	1.102		1.173
L1		3.39			0.133	
L2	1.14		1.70	0.045		0.067
L3	2.65		2.95	0.104		0.116
Φ		3.6			0.142	

PACKAGE INFORMATION-TO-220C

OUTLINE	UNIT WEIGHT (g/PCS) typ.	TUBE (PCS)	PER CARTON (PCS)
TUBE	2.08	50	5,000